

CLAIMS

What is claimed is:

1. A multiple chip module comprising:
a single interconnect substrate;
at least one RF/IF active circuit chip configured to perform a plurality of RF/IF functions,
said at least one RF/IF active circuit chip being coupled to said single interconnect substrate; and
at least one passive component coupled to said single interconnect substrate; wherein
said single interconnect substrate is configured to enable said multiple chip module to
integrate said plurality of RF/IF functions.